

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	49676	(thin narrow narrower thinned thinning) with (lead leadframe (lead adj frame))	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/11 02:00
L2	3433894	(die chip ic (integrated adj circuit) semiconductor)	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/11 02:01
L3	38878	(chip die) adj5 (pad paddle padding)	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/11 02:01
L4	1206	1 same 2 same 3	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/11 02:02
L5	956	4 and (resin encapsulate encapsulation encapsulating encapsulated)	US_PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/11 02:03